







/1 MATING SIDE: Min 0.76µm (PdNi + Au FLASH)IN ZONE "F" OVER Min 1.27µm Ni (Alternative plating — Min 0.76µm Au plating OVER Min 1.27µm Ni) SOLDER SIDE: WITHIN THE RANGE "C" MIN. 3.0µm TIN OVER Min1.27µm Ni

		REVISIONS			
Р	LTR	DESCRIPTION	DATE	DWN	APVD
	С3	Added Sheet 3	11JUL2023	BGC	PS

EMPFOHLENES LEITERPLATTEN LAYOUT

2

RECOMMENDED PCB-LAYOUT (L-2.54)8.2

		KONTAKTSTIFT / CONTACT PIN	CuZn	1	2
		STIFTGEHÄUSE / PIN HOUSING	PCT-GV	SCHWARZ / BLACK	1
		BENENNUNG EINZELTEIL PART DESCRIPTION	WERKSTOFF MATERIAL	OBERFLÄCHE / FARBE SURFACE / COLOR	SI No
THIS DRAWING IS A C	ONTROLLED DOCUMENT	DWN 16SEP1998 F.REICHARDT CHK 16SEP1998 M.SCHAARSCHMIDT	=TE	TE Connectivity Ltd.	•
DIMENSIONS:	TOLERANCES UNLESS OTHERWISE SPECIFIED:	APVD – NAME	MOMODIL II DIN HEM		

1.27

AMPMODU II PIN HEADER PACKED IN BLISTER PRODUCT SPEC 108-18012
APPLICATION SPEC SIZE CAGE CODE DRAWING NO A2 00779 G-1241050 WEIGHT SEE TABLE SEE TABLE CUSTOMER DRAWING

1471-9 (1/15)

RESTRICTED TO

1 of 3



